Test Data
For PMP7958
5/21/2013
**FABRICATION**

Board Dimensions: 4” x 1.1”

**Top Side**

![Top Side Image]

**Bottom Side**

![Bottom Side Image]
The thermal image was taken with the input voltage at 600V, and the load set to 1.5 Amps. The board was left running for twenty minutes. The PCB had a consistent temperature of 32°C to 42°C. The MOSFET operated close to 63°C.
Efficiency Curve Data

PMP7958 Efficiency

Efficiency Curve Data (Close up)

PMP7958 Efficiency

400V Efficiency
500V Efficiency
300V Efficiency
600V Efficiency
Load Transient at 300Vin; Iout Transient from 0.5A - 1.5A
Load Transient at 400Vin; Iout Transient from 0.5A - 1.5A
Load Transient at 500Vin; Iout Transient from 0.5A - 1.5A
Load Transient at 600Vin; Iout Transient from 0.5A -1.5A
SW at 300Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 400Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 500Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 600Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 300Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 400Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 500Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
SW at 600Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Startup at 300Vin and 0A Load
Startup at 400Vin and 0A Load
Startup at 500Vin and 0A Load
Startup at 600Vin and 0A Load
Startup at 300Vin and Full Load
Startup at 400Vin and Full Load
Startup at 500Vin and Full Load
Startup at 600Vin and Full Load
Ripple at 300Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation; Cursors used for reference)
Ripple at 400Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation; Cursors used for reference)
Ripple at 500V in; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation; Cursors used for reference)
Ripple at 600Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation; Cursors used for reference)
Short Circuit at 300Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit at 400Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit at 500Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit at 600Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit Recovery at 300Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit Recovery at 400Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit Recovery at 500Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
Short Circuit Recovery at 600Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)
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